



## Product Change Notice

**Notice: #150106 MSL 4 Upgrade**

**Date: January 6, 2015**

### **To Our Valued Customer:**

We appreciate your use of VI Chip products. Our commitment to customer satisfaction is demonstrated by our notification to you of the following change.

### **Description:**

The FULL and HALF sized VI Chip packages will be upgraded from MSL 6 (245 °C) & MSL 5 (225 °C) to MSL 4 (245 °C) by the use of a new mold compound.

For more information on MSL (Moisture Sensitivity Level), please refer to the latest version of IPC-M-109 obtainable through [www.ipc.org](http://www.ipc.org)

### **Products Affected:**

All VI Chip products in the FULL and HALF size packages.

### **Schedule / Date codes:**

Affected products with a date code of 1528 (July 6, 2015) will have the new mold compound and will be marked on shipping materials as MSL 4 capable.

Data sheets will be updated on July 6, 2015.

### **Action Required:**

No actions are required.

This improvement may allow for improvements in customer assembly processes.

Contact your local Vicor representative for more information.

### **Technical Marketing contact:**

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